

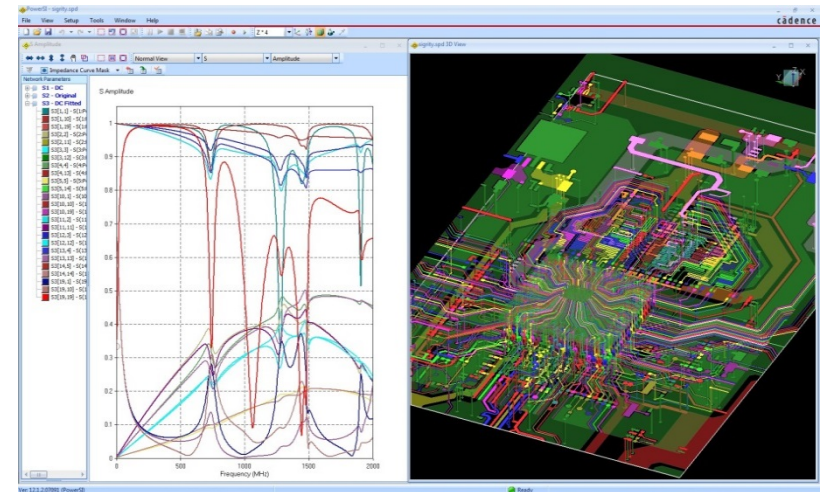


OrCAD Sigrity ERC

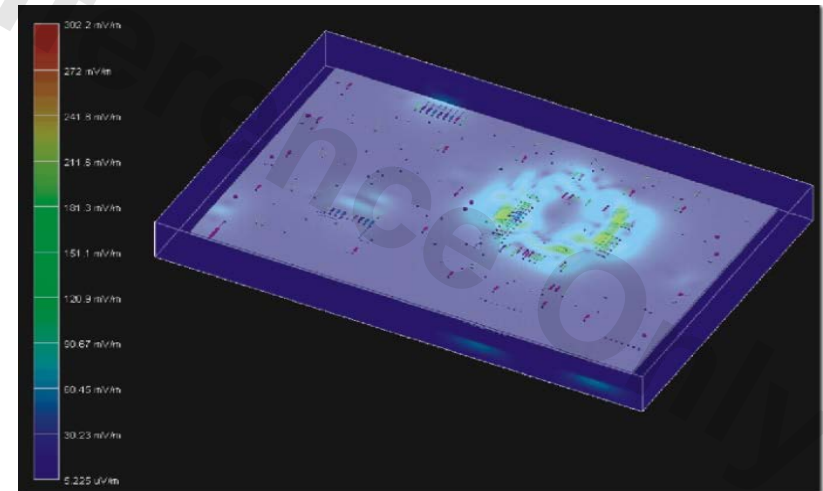
Josh Moore – Product Management Director
Cadence OrCAD Solutions

Cadence Sigrity – Industry-leading SI / PI Solution

- Product of choice for power and signal integrity analysis
 - Integration with full wave 3D EM solver
- Layout-based frequency-domain SI / PI simulation
 - Highly accurate modeling of PCB structures
- Single-ended and mixed-mode results and post-processing
- Unique capability for ensuring accuracy down to DC
- Targeted workflows to streamline setup operations

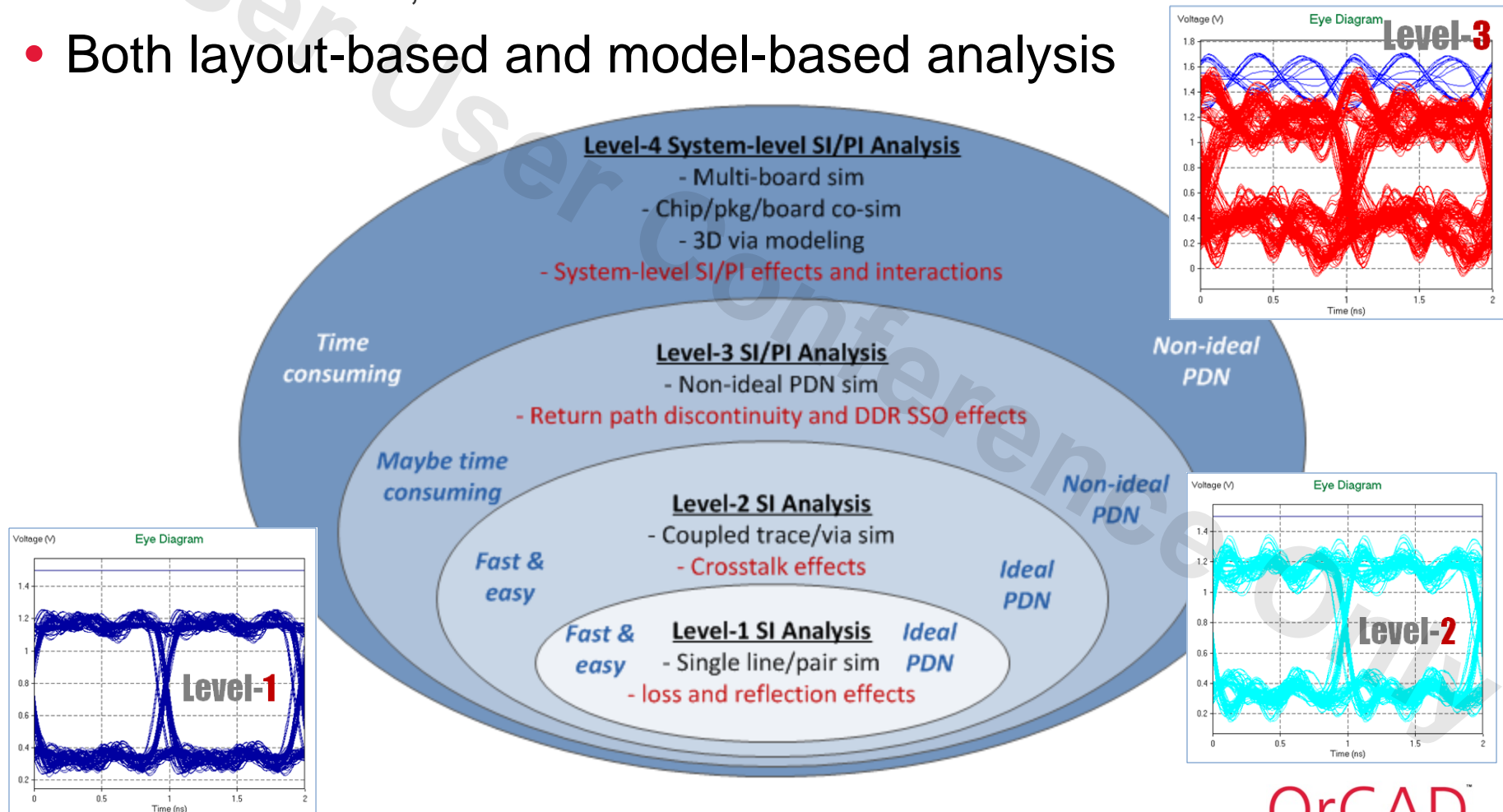


Frequency domain SI, PI and EMC



Different SI / PI / EMI Levels for Different Needs

- Simulations and analysis can be done at four levels
 - Based on considerations of trace / via couplings, non-ideal PDN, etc.
- Both layout-based and model-based analysis



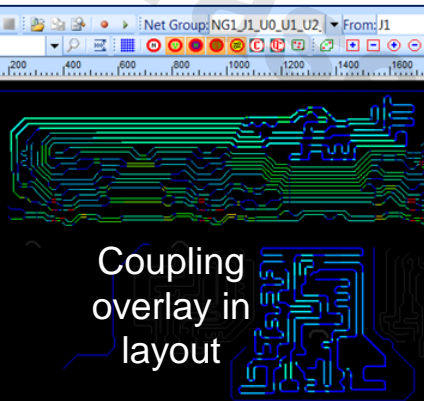
Layout-based, Time-domain SI / PI Simulation

- SPEED2000™ is industry's only layout-based, time-domain SI / PI solution
- Five workflows for SI / PI analysis from level 1 to 3

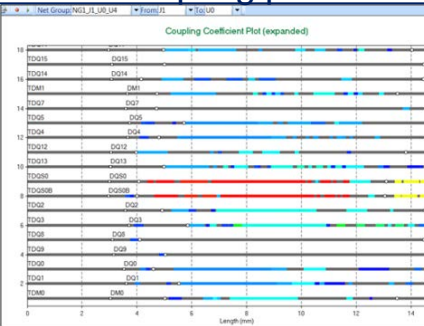
Workflow 1 General SI Simulation	Workflow 2 Trace Impedance/ Coupling Check	Workflow 3 SI Performance Metrics Check	Workflow 4 DDR Simulation	Workflow 5 Time-domain PDN Simulation
<p>Mainstream SI <i>L1/L2 for fast sim</i></p> <p>Easy to setup; Sim runs fast</p> <p>Waveforms & measurements</p>	<p>Geometry based</p> <p>Trace impedance, coupling & reference check for entire board or net groups</p> <p>Results tables; Results plots; Layout overlay; Layout x-probing</p>	<p>Simulation based <i>L1/L2 for fast sim</i> <i>L3 for non-ideal PDN</i></p> <p>Loss, reflection, xtalk check, typically by net groups</p> <p>Waveforms; Xtalk v_max & v_min</p>	<p>Layout-based DDR simulation <i>L1/L2 for fast sim</i> <i>L3 for SSO</i></p> <p>No s-parameter model needed for on-board DRAMs</p> <p>Waveforms & measurements</p>	<p>Layout-based TD PDN sim</p> <p>PDN chip-pkg- board co-sim with -Vltus die mode -XcitePI IO model with die grid</p> <p>Voltage / current distributions; dynamic noise propagation</p>

Geometry- and Simulation-based Layout Checks

Electrical Rules Checks

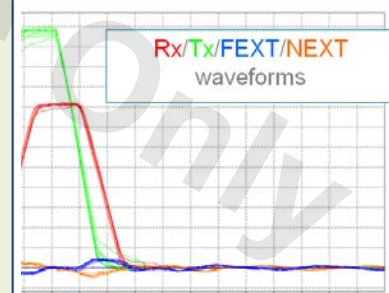
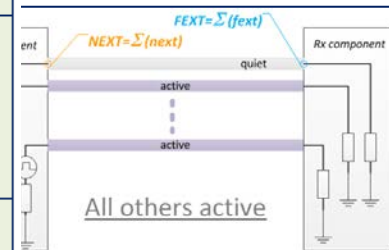
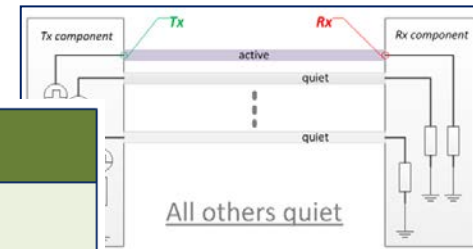


Coupling plot



Coupling table

Net	Length (mm)	Trace Name	Length (mm)	% of its net length	Coupled Lines	Coupling Coefficient
A1	177.72	Trace3000_A1	2.443	1.38%		
A11	136.476	Trace3000_A11	0.444	0.32%		
A2	138.676	Trace3000_A2	0.433	0.31%		
A3	137.888	Trace3000_A3	0.261	0.22%		
A4	138.942	Trace3000_A4	0.432	0.31%		
A5	143.174	Trace3000_A5	1.288	0.9%	Trace3002_Auto_2344-A6	0.034
A6	137.164	Trace3000_A6	0.833	0.61%	Trace3002_Auto_2343-A6	0.034
A7	135.712	Trace3000_A7	0.718	0.53%	Trace3002_Auto_2327-A6	0.034
A8	137.251	Trace3000_A8	0.793	0.58%	Trace3002_Auto_2328-A6	0.034
A9	138.072	Trace3000_A9	0.698	0.51%	Trace3002_Auto_2330-A6	0.034
A10	135.603	Trace3000_A10	0.803	0.59%	Trace3002_Auto_2337-A6	0.034
A11	141.138	Trace3000_A11	0.207	0.15%	Trace3002_Auto_2319-A6	0.034
A12	139.030	Trace3000_A12	0.261	0.19%	Trace3002_Auto_2320-A6	0.034
A13	137.053	Trace3000_A13	0.419	0.31%	Trace3002_Auto_2323-A6	0.034
A14	137.986	Trace3000_A14	1.254	0.91%		
A15	138.146	Trace3000_A15	0.297	0.22%	Trace3002_Auto_2379-A6	0.034
A16	137.164	Trace3000_A16	1.119	0.81%		

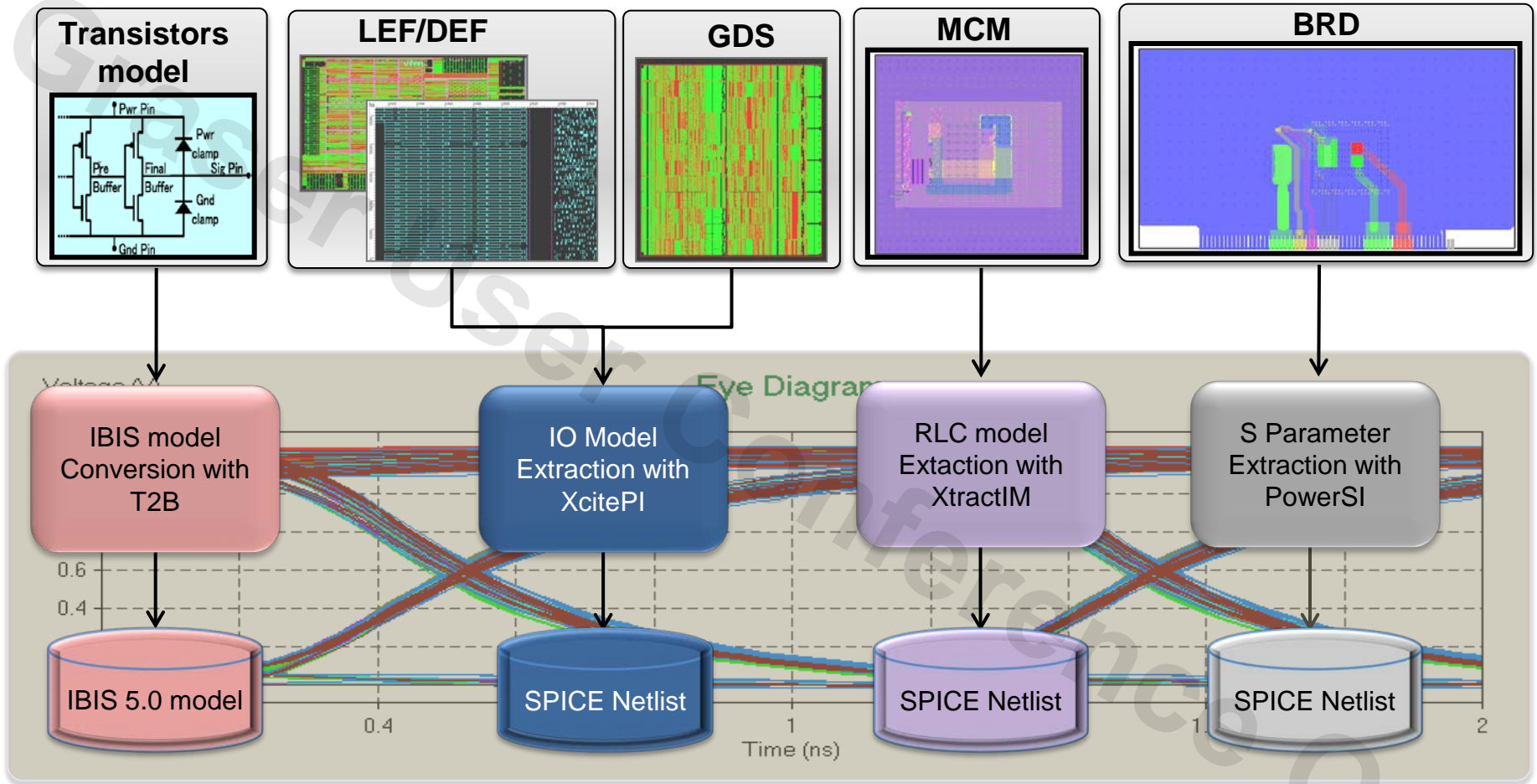


Trace Impedance/Coupling Check	SI Metrics Check
Geometry-based	Simulation-based
Micro, individual, segment-level view (coupling %, Ω & mm)	Macro, combined net-level , view (mv & ps)
<u>Options</u> Check all nets Check selected nets Check nets in net groups	<u>Options</u> Level-1 simulation Level-2 simulation Level-3 simulation
<u>Results</u> Coupling coefficient Impedance Trace reference Summary & detailed tables Expanded & collapsed plots Layout overlay Layout cross probing HTML report	<u>Results</u> Waveforms: Tx / Rx / NEXT / FEXT v_min & v_max SI performance metrics HTML report



SI Barriers for PCB Designers

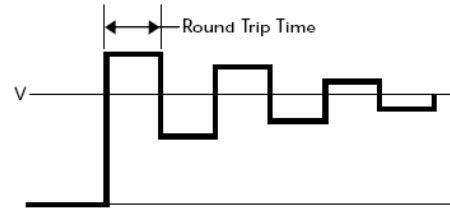
Complex Flow for Simulation and Verification



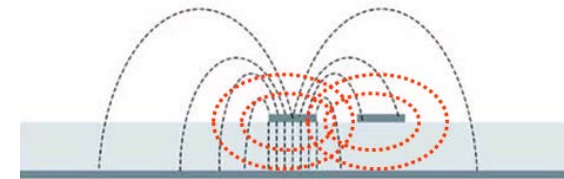
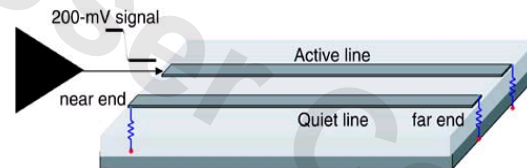
- Comprehensive SI / PI simulation and analysis relies on experienced, well trained engineers with sophisticated tools

Common SI Analysis Needs to be Simple

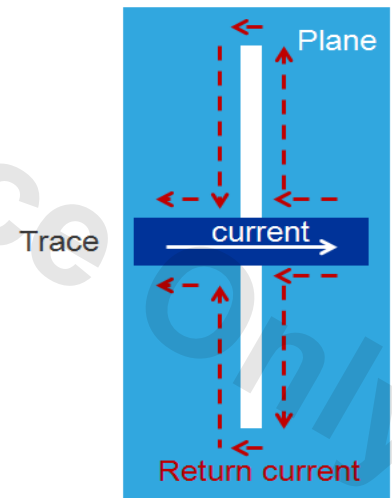
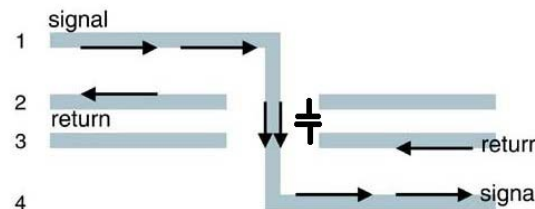
- Reflections (ringing)
 - Impedance mismatch



- Crosstalk
 - Electromagnetic coupling between adjacent signal lines

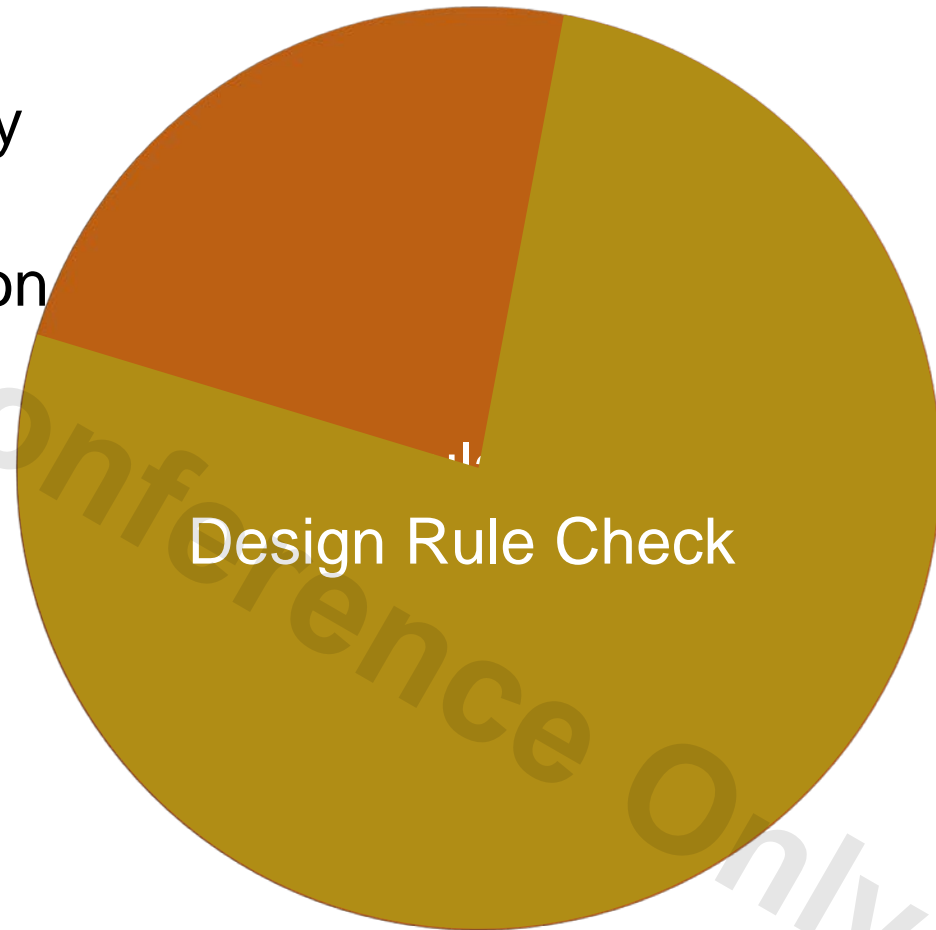


- Return path discontinuity
 - Layer transitions or plane split crosses



Simulation and Design Rule Check

- Ideally, designs should be 100% driven and validated by simulation
- Typically, pre-layout simulation results drive design rules
- Only small portion covered by simulation
- PCB DRCs usually contain only dimension information such as length, width, distance, spacing, etc.
- What do constraints / DRCs forget to tell you?



DRC Correct or Electrically Correct?

- Simple design rule checks for dimension will not validate electrical characteristics

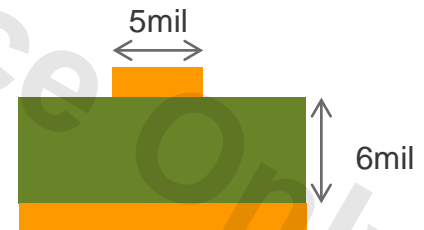
Question:

1. Are the DRC results of these 2 structures the same or different? **Same**
2. Do these 2 structures have the same or different electrical properties? **Different**
3. Do these 2 structures have the same impedance or not?

Case 1:

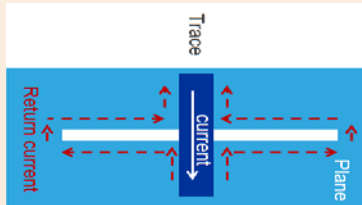


Case 2:

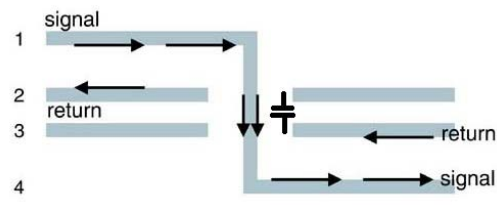


DRC Correct or Electrically Correct?

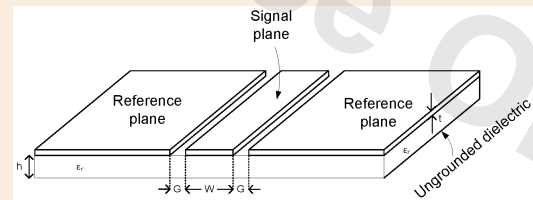
- Pre-layout simulation, defines a trace width to be 5 mils for a target impedance
 - The following routed trace results in **no DRC** violation



1. Reference change
2. Cross plane split

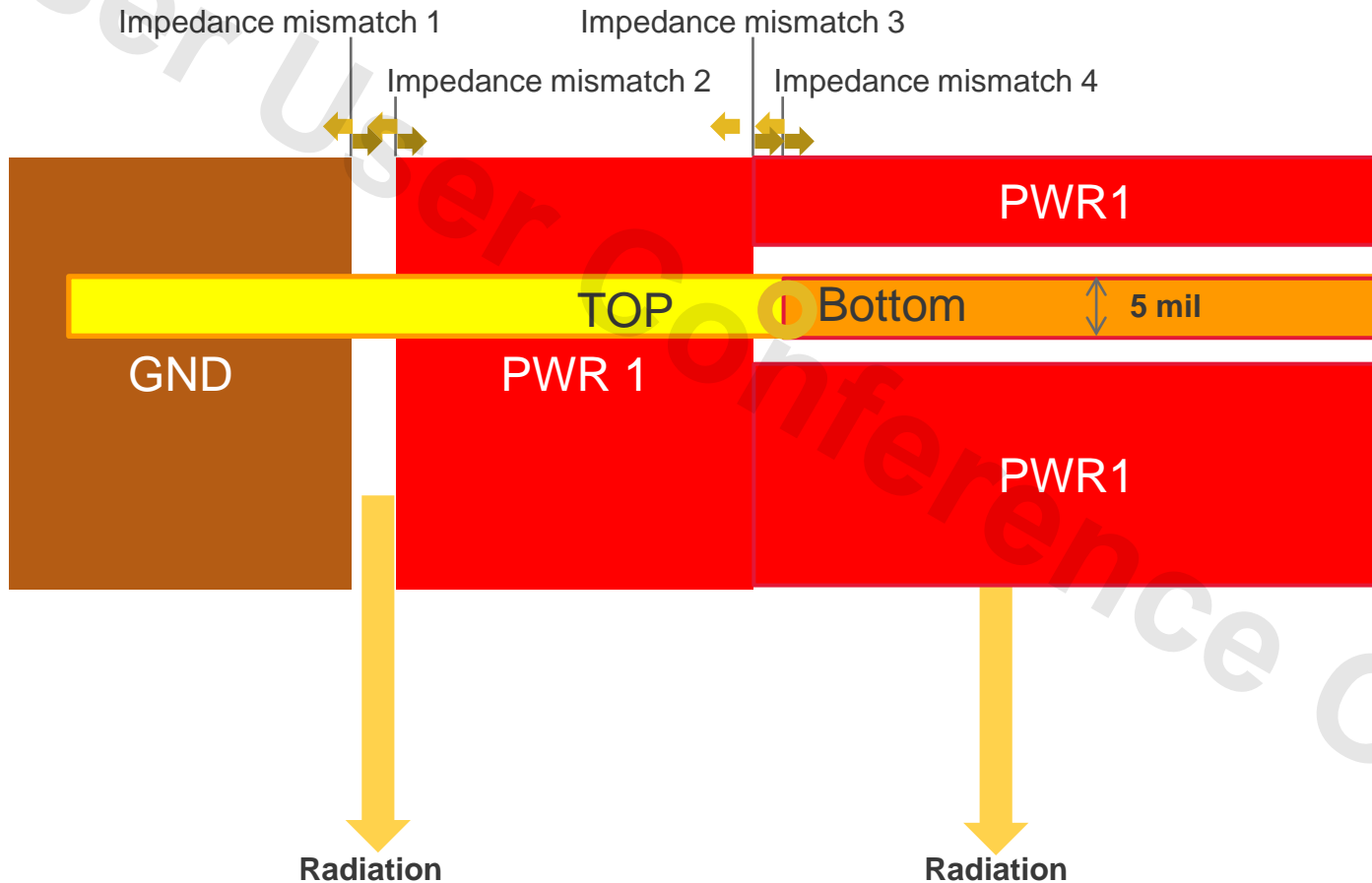


1. Layer Transition



1. Coplanar reference

DRC Correct or Electrically Correct?

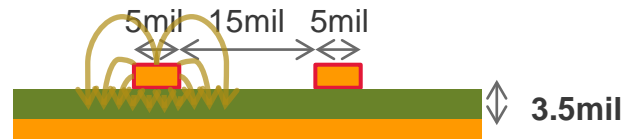


DRC Correct or Electrically Correct?

- To minimize crosstalk, many follow the '3W' rule – set the spacing between critical adjacent traces to 3 times the width of the trace
 - The following routed trace results in **no DRC** violation



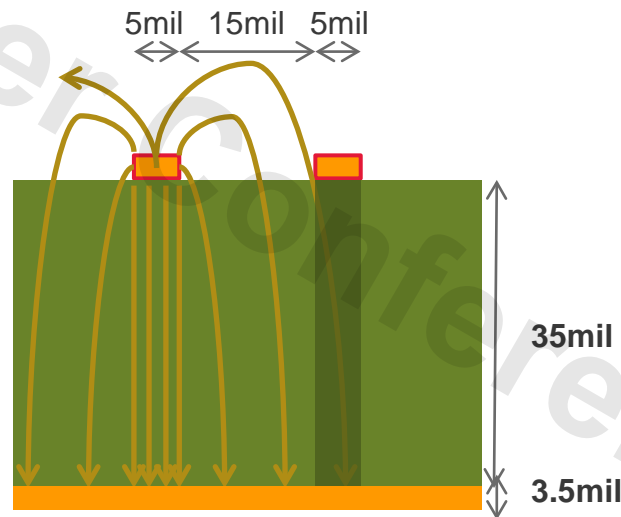
'3W' rule works for the following structure



No DRC violation → No Xtalk issue

DRC Correct or Electrically Correct?

- What if the stack-up looks like the following, will '3W' rule still work?



No DRC violation → Still no Xtalk issue?

How do you know?

DRC Correct or Electrically Correct?

- DRCs only validate **MINIMUM, PHYSICAL** requirements of design constraints
- Do no DRCs mean a good, quality design?
- Can PCB designers identify and address signal quality issues?

How difficult is it to setup?
Is it easy to use?
Do I have to be an SI expert?
Is it expensive?





OrCAD Sigrity Technology for PCB Designers

Electrical Rule Checks with OrCAD Sigrity ERC

- ERCs are better than DRCs for signal quality validation
 - Go beyond **MINIMUM, GEOMETRY-BASED** constraint validation
- Easy to use, minimal setup
- PCB designers can identify and address signal quality issues

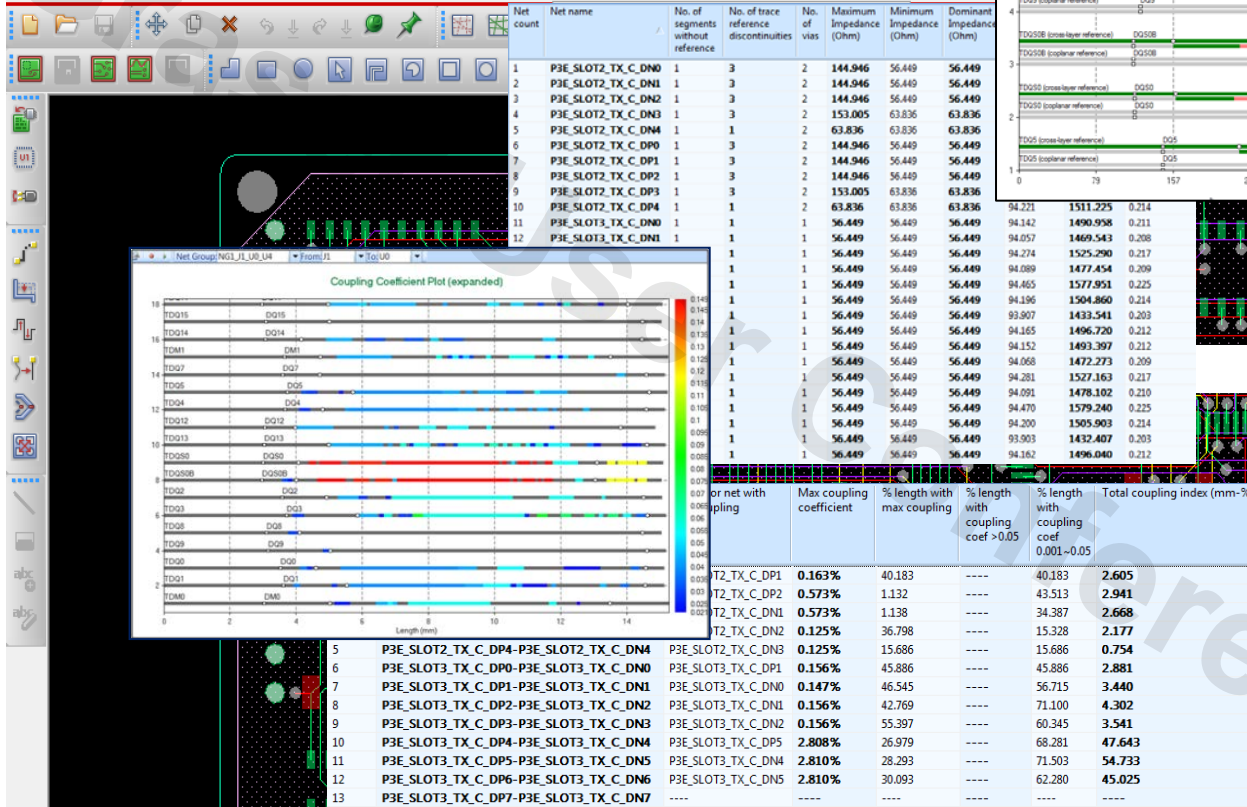


OrCAD Sigrity ERC (coming 2015 / 17.0 & QIRs)

- No complex modeling / setup required
- Electrical checks include
 - SI Metrics (Level 1 & Level 2)
 - Differential Pair Serial Link Screening
 - Trace impedance check
 - Trace return path check
 - Via return path check
 - Trace coupling check
 - Net coupling check
 - Additional future checks
- OrCAD FloorPlanner
 - Place and route edits only
 - Cross-probe (pan / highlight / zoom) between analysis & layout

OrCAD Sigrity ERC Flow

File Edit View Display Setup Shape Logic Place Route Analyze Tools Help



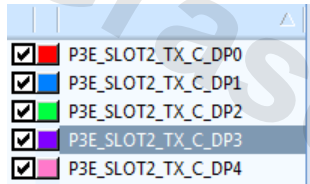
Trace Impedance / return path

Coupling / metrics

Design modification

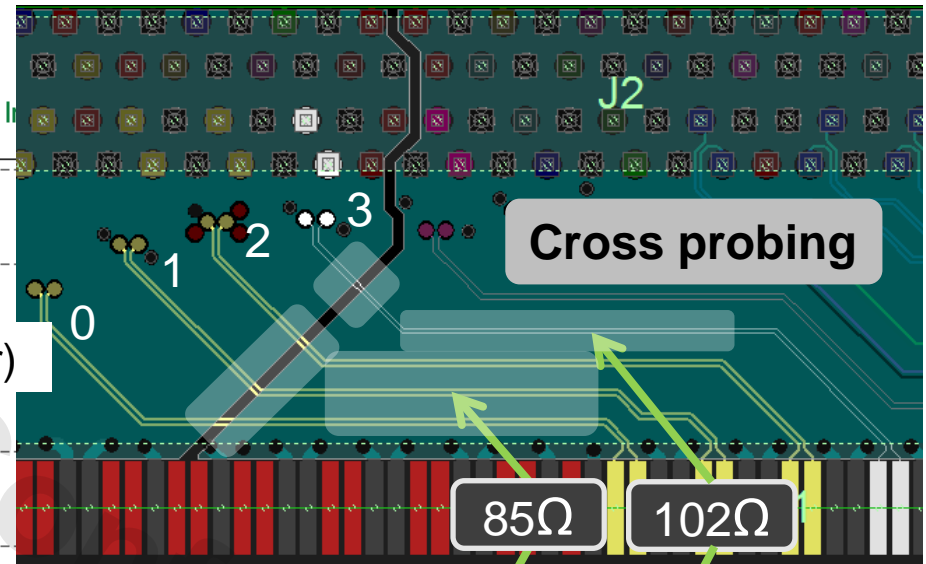
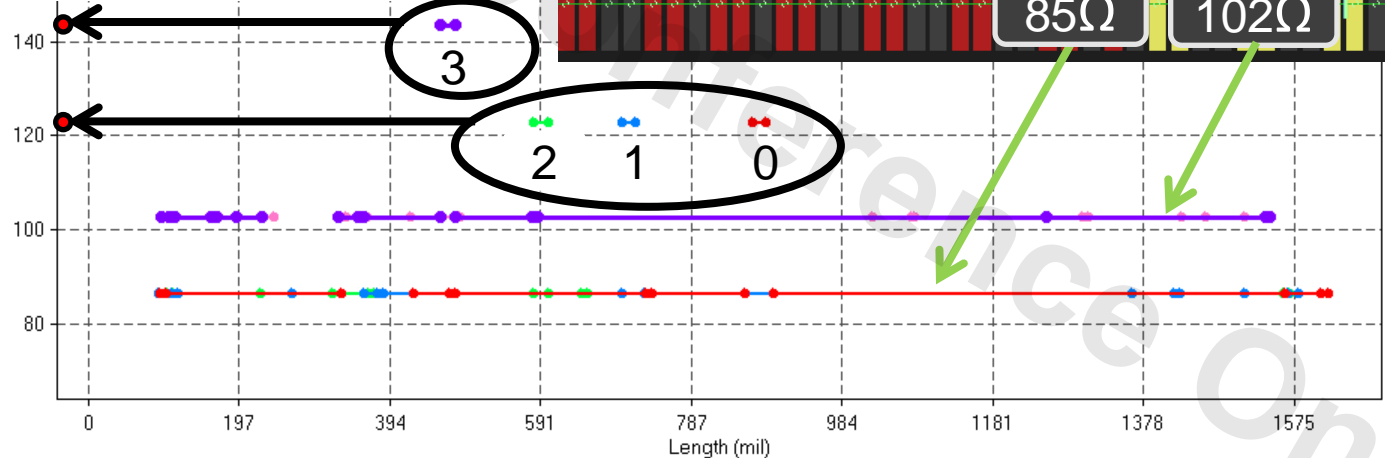
Trace Impedance Check

Visual plot



Impedance (Ohm)

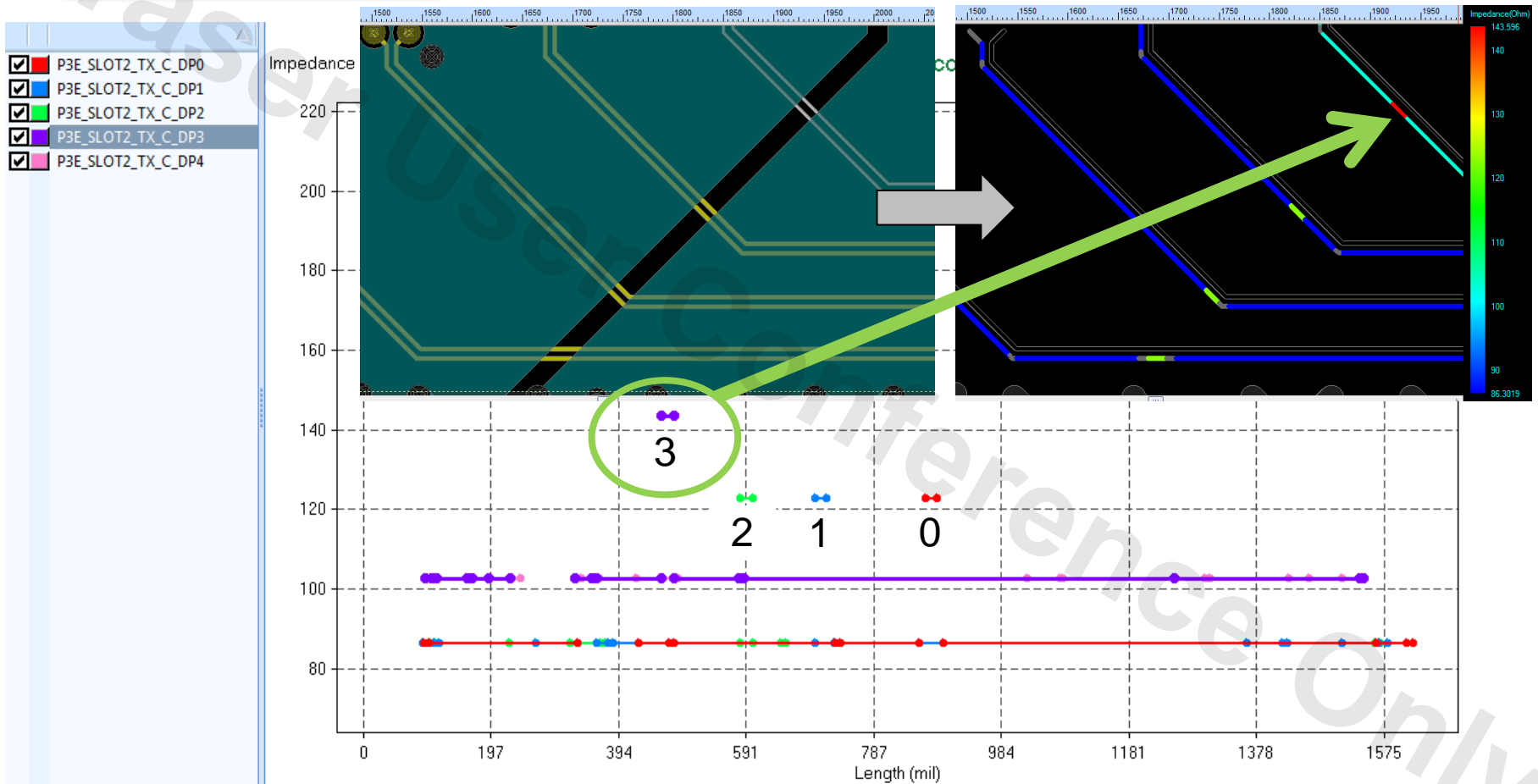
- This check helps identify
 - Wrong trace width spacing (e.g. diff. pair)
 - Plane split cross
 - Trace impedance variances



- Visually or tabular results for trace impedance check shows trace segment(s) mismatch vs. target impedance

Trace Impedance Check

Cross Probing



- Cross probing allows issues to be quickly identified

Trace Impedance Check

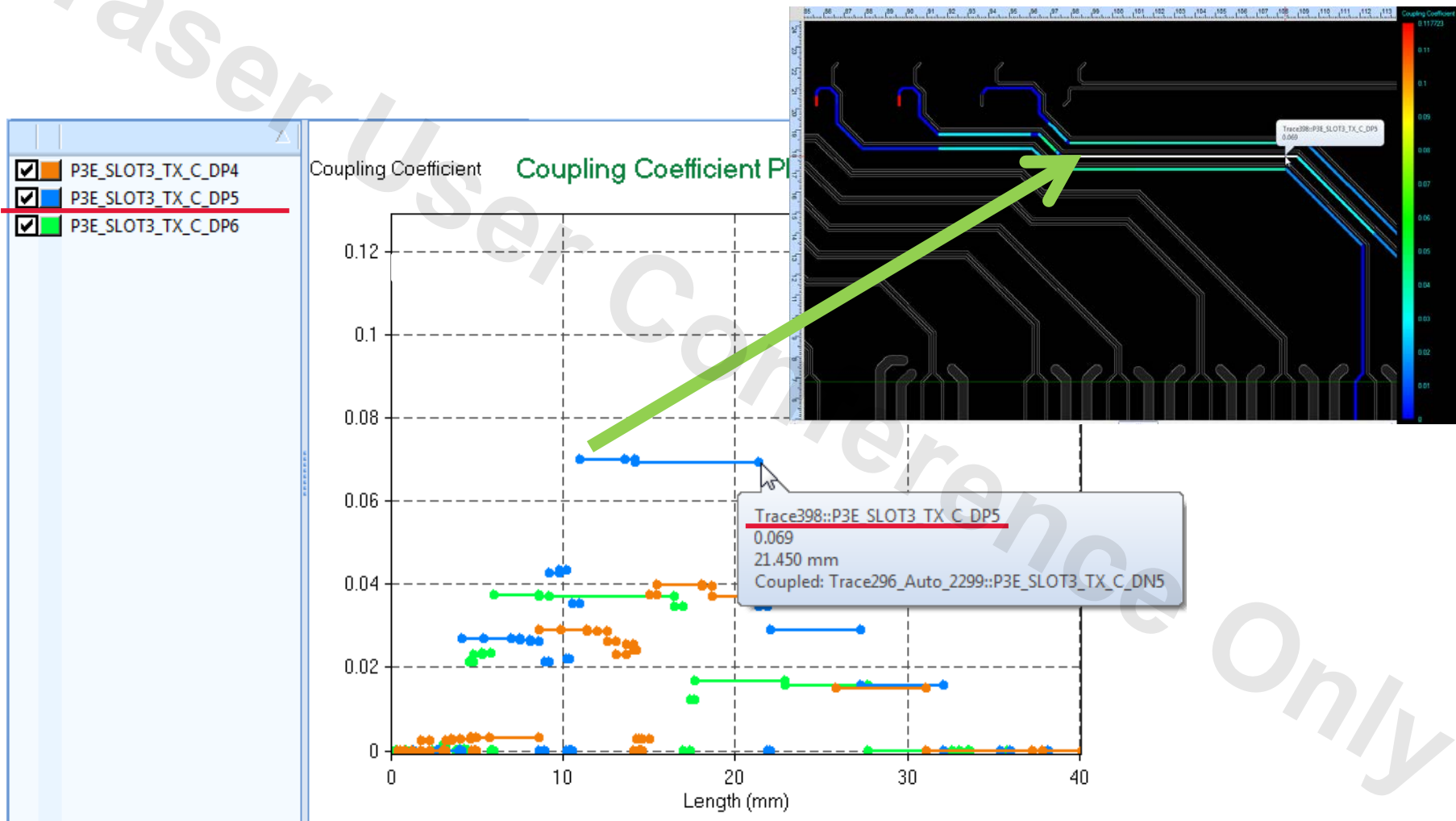
Tabular Results

Net count	Net name	No. of segments without reference	No. of trace reference discontinuities	No. of vias	Maximum Impedance (Ohm)	Minimum Impedance (Ohm)	Dominant Impedance (Ohm)	Dominant Imp Length (%)	Trace total length (mil)	Trace delay(ns)
1	P3E_SLOT2_TX_C_DN0	1	3	2	144.946	56.449	56.449	92.921	1633.158	0.233
2	P3E_SLOT2_TX_C_DN1	1	3	2	144.946	56.449	56.449	93.168	1583.722	0.225
3	P3E_SLOT2_TX_C_DN2	1	3	2	144.946	56.449	56.449	93.186	1575.168	0.224
4	P3E_SLOT2_TX_C_DN3	1	3	2	153.005	63.836	63.836	93.074	1549.678	0.220
5	P3E_SLOT2_TX_C_DN4	1	1	2	63.836	63.836	63.836	94.228	1513.121	0.214
6	P3E_SLOT2_TX_C_DP0	1	3	2	144.946	56.449	56.449	92.923	1633.643	0.233
7	P3E_SLOT2_TX_C_DP1	1	3	2	144.946	56.449	56.449	93.221	1583.404	0.225
8	P3E_SLOT2_TX_C_DP2	1	3	2	144.946	56.449	56.449	93.184	1574.865	0.224
9	P3E_SLOT2_TX_C_DP3	1	3	2	153.005	63.836	63.836	93.059	1546.528	0.219
10	P3E_SLOT2_TX_C_DP4	1	1	2	63.836	63.836	63.836	94.221	1511.225	0.214
11	P3E_SLOT3_TX_C_DN0	1	1	1	56.449	56.449	56.449	94.142	1490.958	0.211
12	P3E_SLOT3_TX_C_DN1	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
13	P3E_SLOT3_TX_C_DN2	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
14	P3E_SLOT3_TX_C_DN3	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
15	P3E_SLOT3_TX_C_DN4	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
16	P3E_SLOT3_TX_C_DP0	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
17	P3E_SLOT3_TX_C_DP1	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
18	P3E_SLOT3_TX_C_DP2	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
19	P3E_SLOT3_TX_C_DP3	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208
20	P3E_SLOT3_TX_C_DP4	1	1	1	56.449	56.449	56.449	94.057	1460.543	0.208

- Cross plane split?
- Any trace segment mismatch? Cross plane split?
- Too much breakout neck length?
- Too much MS/SL routing difference in a group?
- The same trace length means the same trace delay?
- Routing on MS/SL has different trace delay.

Trace Coupling Check

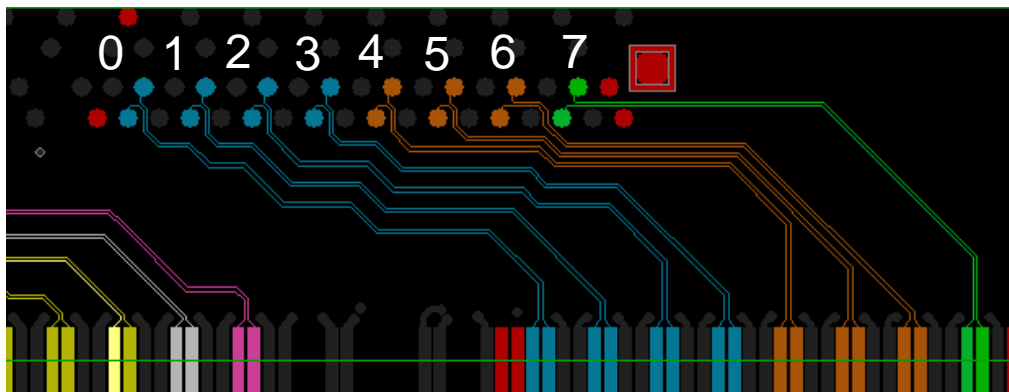
Cross probing helps to easily resolve issues



Trace Coupling Check

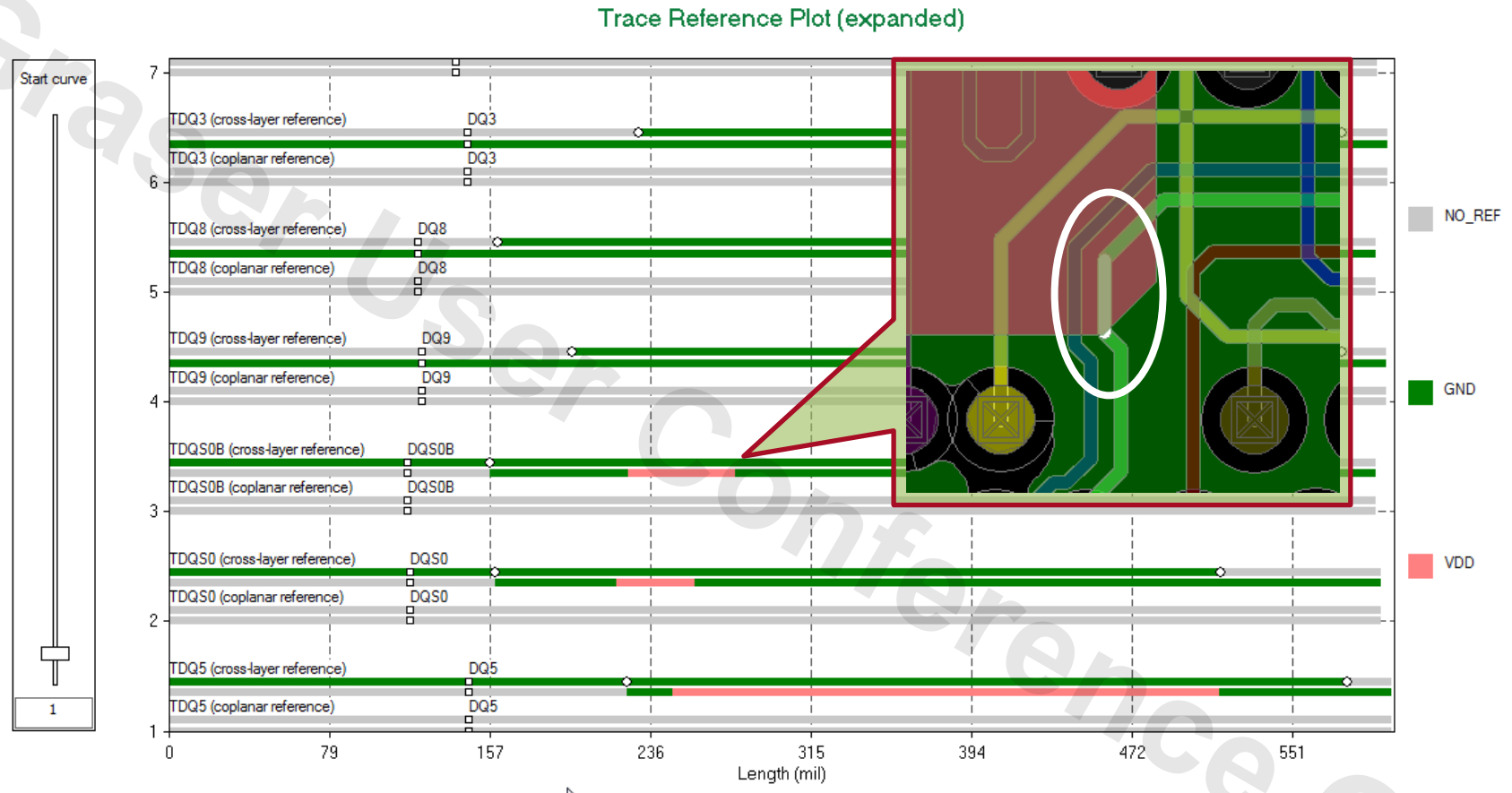
Net count	Net name	Aggressor net with max coupling	Max coupling coefficient	% length with max coupling	% length with coupling coef >0.05	% length with coupling coef 0.001~0.05	Total coupling index (mm-%)
1	P3E_SLOT2_TX_C_DP0-P3E_SLOT2_TX_C_DN0	P3E_SLOT2_TX_C_DP1	0.163%	40.183	----	40.183	2.605
2	P3E_SLOT2_TX_C_DP1-P3E_SLOT2_TX_C_DN1	P3E_SLOT2_TX_C_DP2	0.573%	1.132	----	43.513	2.941
3	P3E_SLOT2_TX_C_DP2-P3E_SLOT2_TX_C_DN2	P3E_SLOT2_TX_C_DN1	0.573%	1.138	----	34.387	2.668
4	P3E_SLOT2_TX_C_DP3-P3E_SLOT2_TX_C_DN3	P3E_SLOT2_TX_C_DN2	0.125%	46.798	----	15.328	2.177
5	P3E_SLOT2_TX_C_DP4-P3E_SLOT2_TX_C_DN4	P3E_SLOT2_TX_C_DN3	0.125%	15.686	----	15.686	0.754
6	P3E_SLOT3_TX_C_DP0-P3E_SLOT3_TX_C_DN0	P3E_SLOT3_TX_C_DP1	0.156%	45.886	----	45.886	2.881
7	P3E_SLOT3_TX_C_DP1-P3E_SLOT3_TX_C_DN1	P3E_SLOT3_TX_C_DN0	0.147%	46.545	----	56.715	3.440
8	P3E_SLOT3_TX_C_DP2-P3E_SLOT3_TX_C_DN2	P3E_SLOT3_TX_C_DN1	0.156%	42.769	----	71.100	4.302
9	P3E_SLOT3_TX_C_DP3-P3E_SLOT3_TX_C_DN3	P3E_SLOT3_TX_C_DN2	0.156%	55.397	----	60.345	3.541
10	P3E_SLOT3_TX_C_DP4-P3E_SLOT3_TX_C_DN4	P3E_SLOT3_TX_C_DP5	2.808%	26.979	----	68.281	47.643
11	P3E_SLOT3_TX_C_DP5-P3E_SLOT3_TX_C_DN5	P3E_SLOT3_TX_C_DN4	2.810%	28.293	----	71.503	54.733
12	P3E_SLOT3_TX_C_DP6-P3E_SLOT3_TX_C_DN6	P3E_SLOT3_TX_C_DN5	2.810%	30.093	----	62.280	45.025
13	P3E_SLOT3_TX_C_DP7-P3E_SLOT3_TX_C_DN7	----	----	----	----	----	----

18X



- Tight coupling pairs
- Max coupling aggressor
- Dangerous vs. safe coupling
→ **18X** (= 2.81% / 0.156%)

Trace Reference Check



- Trace cross layer reference shows the net names for the reference plane shapes directly above and below the corresponding trace segment
- Trace coplanar reference shows the net names for the reference plane shapes next to the corresponding trace segment on the same layer

Summary / Benefits

- ERCs are better than DRCs for signal quality validation
 - Identify issues geometry-based DRCs miss
- OrCAD Sigrity ERC specifically designed for PCB designers leveraging industry-leading Cadence Sigrity technology
 - Easy to use, minimal setup
 - Cross-probing
- Actionable results to identify and quickly address signal quality issues

OrCADTM

CADENCE PCB SOLUTIONS

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